



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-02-09
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	B5D7*U002HAZ	A	MU1A	2015-02-09
Amount	UoM	Unit type	ST ECOPACK Grade	
1498.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	24.38 - 6.35 - 3.3	18	Through-hole	
Comment	Package: PDIP 18 .3 Cu 0.4; MDF valid for L6202			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BSD7*U002HAZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	14.818	mg	supplier	die	Silicon (Si)	7440-21-3		14.420	mg	973141	9626
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.089	mg	6006	59
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.081	mg	5466	54
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.125	mg	8436	83
Die or Dies				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.008	mg	540	5
Die or Dies				supplier	back side metallization	Gold (Au)	7440-57-5		0.022	mg	1485	15
Die or Dies				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.073	mg	4926	49
Leadframe	Copper & its alloys	704.085	mg	supplier	alloy	Copper (Cu)	7440-50-8		702.845	mg	998239	469189
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.704	mg	1000	470
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.211	mg	300	141
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.325	mg	462	217
Soft solder	Solder	9.353	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	9.119	mg	974981	6087
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.140	mg	14968	93
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.094	mg	10050	63
Bonding wire	Precious metals	2.203		supplier	wire	Gold (Au)	7440-57-5		2.203	mg	1000000	1471
encapsulation	Other inorganic materials	766.101	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		103.424	mg	135000	69041
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		42.136	mg	55001	28128
encapsulation				supplier	mold compound	Tetrabromobisphenol	79-94-7		19.152	mg	24999	12785
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		2.298	mg	3000	1534
encapsulation				supplier	mold compound	Antimony pentoxide	1314-60-9		9.193	mg	12000	6137
encapsulation				supplier	mold compound	carbon black	1333-86-4		3.831	mg	5001	2557
encapsulation				supplier	mold compound	Mixed siloxanes	Proprietary		11.492	mg	15001	7672
encapsulation				supplier	mold compound	Acrylic resin	9003-01-4		15.322	mg	20000	10228
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		551.591	mg	719998	368218
encapsulation				supplier	mold compound	Silica Cristobalite	14464-46-1		3.831	mg	5001	2557
encapsulation				supplier	mold compound	Quartz	14808-60-7		3.831	mg	5001	2557
connections coating	Solder	1.440	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.440	mg	1000000	961